Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **1 N.G**
2. **1A1**
3. **2Y4**
4. **1A2**
5. **2Y3**
6. **1A3**
7. **2Y2**
8. **1A4**
9. **2Y1**
10. **GND**
11. **2A1**
12. **1Y4**
13. **2A2**
14. **1Y3**
15. **2A3**
16. **1Y2**
17. **2A4**
18. **1Y1**
19. **2 N.G**
20. **VCC**

**.039”**

**2 1 20 19**

**18**

**17**

**16**

**15**

**14**

**13**

**3**

**4**

**5**

**6**

**7**

**8**

**9 11 12**

 **10**

**2 4 0**

**L S**

**.077”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential: GND**

**Mask Ref: LS 240**

**APPROVED BY: DK DIE SIZE .039” X .077” DATE: 8/29/22**

**MFG: TEXAS INSTRUMENTS THICKNESS .015” P/N: 54LS240**

**DG 10.1.2**

#### Rev B, 7/1